

DATA-2017: IEEE INTERNATIONAL WORKSHOP on DEFECTS, ADAPTIVE TEST, YIELD AND DATA ANALYSIS

Will be held in conjunction with ITC 2017, on Nov. 2-3, 2017,
In Fort Worth, TX



GENERAL CHAIR

Jeffrey Roehr, Test Consultant

PROGRAM CHAIR

Wesley Smith, Mentor

FINANCE CHAIR

Sagar Kekare, KLA-Tencor

PUBLICITY & WEB CHAIR

Sankaran Menon, Intel

PUBLICATIONS CHAIR

Chintan Patel, UMBC

PANEL CHAIR

Anne Meixner, The Engineers' Daughter

LOCAL ARRANGEMENTS

David Park, Optimal+

TEST STANDARDS CHAIR

Al Crouch, SiliconAid

EU LIAISON

Dirk De Vries, Qualtera

STEERING COMMITTEE

Jennifer Dworak, SMU
Jeffrey Roehr, Test Consultant
Sankaran Menon, Intel
Adit Singh, Auburn Univ.
M. Tehranipoor, U of Florida
Hank Walker, Texas A&M
Hans Manhaeve, Ridgetop
Jim Plusquellic, U. NM

PROGRAM COMMITTEE

Rob Aitken, ARM
Nemat Bidokhti, Huawei
Sreejit Chakravarty, Intel
John Carulli, Global Foundries
Patrick Girard, LIRMM, France
Ajay Khoche, Smart Connected Systems
Mike Laisne, Dialog Semi
Rene Segers, Consultant
Amit Nahar, TI
Suriyaprakash Natarajan, Intel
Jay Orbon, Consultant
John Potter, Global Foundries
Rajesh Raina, NXP
Claude Thibeault, ETS, Canada
Li C. Wang, UCSB
Xiaoqing Wen, KIT, Japan
Qiang Xu, CUHK, Hong Kong

CALL FOR PAPERS AND PARTICIPATION THEME: "Data in the Product Lifecycle"

In test, we use data every day. Yield data, throughput data, statistical data, reliability data, outlier data, general production data are all in everyday use. However, data means much more than that. Advances in our industry allow data from wafer fab to be reused in studying system level test results. Field failure studies now routinely uses wafer probe data to understand root cause. Data has now become a product life cycle requirement—cradle to grave. Today access to the data has become an issue; the control and sharing of data among business partners. How to efficiently process data to extract the golden nuggets of useful information amid the gigabytes of unimportant noise remains a focus and a challenge for test professionals.

The Organizing Committee for the DATA-2017 Workshop is soliciting papers in: semiconductor test, yield analysis, product learning, and quality improvement. Of particular interest are advanced techniques and new tools for the use of data during the entire product life cycle, with special attention to how data can be used to change and alter test flows and decisions (adaptive test). Preference will be given to real-world case studies.

Ideas or proposals for Embedded Tutorials, Debates, Panel Discussions and Poster style "Spot-Light" presentations describing industrial experiences or research are also invited.

Suggested Topics

Real Time Analysis Methods
Real Time Test Process Monitoring
Yield Learning and Analysis
Analog Fault Modeling and Coverage
Analog Effects in Digital Logic
Embedded Instrumentation (iJTAG)
Advanced DPPM Reduction & Reliability Improvement Techniques

Data Acquisition & Transport
Adaptive Test for Product Engineers
Data Analysis Methods, Including Multivariate Data
Fault Localization and Diagnosis
Data Storage and Security
I/O Test, Tuning, and Adjustment
Product and Project Case studies

To present at the workshop, send to smith.wesley@siemens.com a PDF version of an extended abstract or a full paper (Max 10 pages, double column, 11pt font size, [IEEE proceeding format](#)) by **September 20, 2017**. Each submission should include full name and address of each author, affiliation, telephone number, and Email address. Camera-ready papers for inclusion in the digest of papers will be due on **October 16, 2017**.

AUTHOR'S SCHEDULE

Submission Date:
Notification of Acceptance:
Camera Ready Paper (.pdf):
Final Presentation Slides (.ppt):

Web-site at: <http://DATA.ttc-events.org/>

September 20, 2017
October 2, 2017
October 16, 2017
October 23, 2017

General Information:

Jeff Roehr
Test Consultant.
E-mail: JLRoehr@Gmail.com

Technical Program Submissions:

Wesley Smith
Mentor, a Siemens Company
E-mail: smith.wesley@siemens.com

DATA-2017 is sponsored by:

